

CONTENTS

	Page Number
ACKNOWLEDGEMENT	i
ABSTRACT	ii
CONTENTS	iii
LIST OF TABLES	vi
LIST OF FIGURES	vii
LIST OF APPENDIXS	ix
CHAPTER 1: INTRODUCTION	
1.1 General Principles of Electrodeposition	1
1.1.1 Standard Potentials of Copper	1
1.1.2 Electroplating	3
1.1.3 Rate of Deposition	6
1.1.3.1 Faraday's Laws	6
1.1.3.2 Current Efficiency	6
1.1.3.3 Current Density	7
1.2 Nucleation and the Mechanism of the Electrodeposition of Metals	8
1.2.1 Nucleation	8
1.2.2 The Mechanism of the Electrodeposition of Metals	10
1.3 Electrode Kinetics	15
1.3.1 The Rate of Electron Transfer	16
1.4 Mass Transport	20
1.4.1 Diffusion	21
1.4.2 Convection	22
1.4.3 Migration	23
1.5 Voltammetry	24
1.5.1 Cyclic Voltammetry	24
1.5.2 EC Reaction	25
1.6 Scanning Electron Microscopy	28
1.6.1 Instrumentation	28
1.6.1.1 Electron Sources	29
1.6.1.2 Electron Optics	30
1.6.1.3 Detector	31
1.6.2 The Interactions of Electron Beams with Solids	32
1.6.2.1 Elastic Scattering	32
1.6.2.2 Inelastic Interaction	33
1.7 Properties of Copper	34
1.7.1 Chemical Properties	34

1.7.2 Physical Properties	35
1.7.2.1 Malleable	35
1.7.2.2 Electrical Conductivity	36
1.7.2.3 Thermal Conductivity	37
1.7.2.4 Corrosion Resistant and Application	38
1.8 Application of Copper Plating	40
1.8.1 Electrodeposition	41
1.8.2 Electropolishing	44
1.9 Objective	45

CHAPTER 2: METHODOLOGY AND MATERIALS

2.1 Chemicals and Materials	46
2.2 Apparatus and Instruments	48
2.3 Fabrication and Polishing of Copper Working Electrode	50
2.3.1 Fabrication of Copper Working Electrode	50
2.3.2 Polishing of Copper Working Electrode	51
2.4 Experiment	52
2.4.1 Bath Solution Preparation	52
2.4.2 Instruments Setting and Operation	53
2.4.2.1 Operation of BAS 100 B/W Electrochemical Workstation (Cyclic voltammetry Mode)	53
2.4.2.2 Operation of Model 363 Potentiostat/ Galvanostat (Plating)	56
2.4.2.2.1 Control E Operation	56
2.4.2.2.2 Control I Operation	58

CHAPTER 3: RESULTS AND DISCUSSION

3.1 Cyclic Voltammetry	60
3.2 The R Square Coefficient	66
3.3 The Mechanism Study	68
3.3.1 Reversible Reaction	68
3.3.2 Irreversible Reaction	72
3.3.3 Effect of Additive	74
3.3.4 Effect of Chloride Ion	75
3.4 Plating Process	77
3.5 Rate of Copper Deposition	89
3.6 Effect of Additive	91
3.7 Surface Morphology of Plated Electrode	93
3.7.1 Dissolution of Copper	95
3.7.2 Plating at Constant Potential	96
3.7.3 Plating at Constant Current	99
3.8 EDX	100
3.9 Problems and Suggestion	101

CHAPTER 4: CONCLUSION

4.1 Cyclic Voltammetry	103
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4.2 Plating Process	104
4.3 SEM	104
REFERENCE	106
APPENDIX	108

LIST OF TABLES

Table	Page Number
1.1.1.1 Standard Potentials in Acidic Solution	2
2.1.1 Composition of copper (II) sulphate anhydrous	47
3.1.1 Peak currents obtained from different scan rates	60
3.1.2 Peak currents obtained from different scan rates	61
3.1.3 Peak currents obtained from different scan rates	62
3.1.4 Peak currents obtained from different scan rates	63
3.1.5 Peak currents obtained from different scan rates	64
3.1.6 Peak currents obtained from different scan rates	65
3.4.1 Current measured due to plating process on copper electrode at constant potential	77
3.4.2 Potential measured due to plating process on copper electrode at constant current	79
3.4.3 Current measured due to plating process on copper electrode at constant potential	81
3.4.4 Potential measured due to plating process on copper electrode at constant current	83
3.4.5 Current measured due to plating process on copper electrode at constant potential	85
3.4.6 Potential measured due to plating process on copper electrode at constant current	87
3.7 Appendix list for the SEM image for the surface of copper discs due to different plating condition	93

LIST OF FIGURES

Figure	Page Number
1.2.2.1 Types of site on a perfect crystal: 1, Kink site; 2, edge site; 3, adatom	11
1.2.2.2 A screw dislocation and its propagation leading to a spiral feature	13
1.2.2.3 Schematic of various growth forms observed in metal deposition: (a) layer growth, (b) ridge growth, (c) block growth, (d) pyramidal growth, and (e) dendritic growth	14
1.2.2.4 The variation of the characteristic growth modes on the normalised current density (I/I_L)	15
1.3.1.1 The variation of current as a function of the potential different	19
1.4.1 Schematic of some of the processes that influence the rate of an electrode reaction	20
1.4.1.1 Diffusion to a large planar surface	21
1.5.1.1 Cyclic voltammogram for a reversible electron transfer reaction	25
1.5.2.1 Cyclic voltammograms showing the influence of chemical reaction on the observed voltammetric behaviour	27
1.6.1.1 Schematic of a SEM	29
2.2.1 A photograph of the cell used. (A) Counter electrode, (B) Working electrode, (C) Nitrogen gas inlet and (D) Reference electrode	49
2.3.1.1 The fabricated copper working electrode	50
2.4.2.1.1 A photograph of a cell and the BAS 100B/W Electrochemical workstation	54
3.1.1 Graph of peak current versus square root of scan rate	61

3.1.2	Graph of peak currents versus square root of scan rates	62
3.1.3	Graph of peak currents versus square root of scan rates	63
3.1.4	Graph of peak currents versus square root of scan rates	64
3.1.5	Graph of peak currents versus square root of scan rates	65
3.1.6	Graph of peak currents versus square root of scan rates	66
3.2.1	Voltammograms	67
3.3.1.1	The potential sweep (a) and corresponding current response (b) for the forward scan fragment	69
3.4.1	Graphs of current versus time for A1, A2, A3, A4 and A5	78
3.4.2	Graphs of potential versus time for A6, A7, A8, A9, A10 and A11	80
3.4.3	Graphs of current versus time for B1, B2, B3 and B4	82
3.4.4	Graphs of potential versus time for B6, B7, B8, B9, B10 and B11	84
3.4.5	Graphs of current versus time for C1, C2 and C3	86
3.4.6	Graphs of potential versus time for C6, C7, C8, C9, C10 and C11	88
3.7.2.1	Surface of copper deposit viewed at 19.42 KX magnification	97
3.7.2.2	Nodules growth viewed at 801 X magnification	99
3.7.3.1	Surface of the copper deposit on copper disc, viewed at 15.61 KX magnification	100

LIST OF APPENDIXS

Appendix	Page Number
A Voltammograms	108
B Voltammograms	114
C Voltammograms	119
D Voltammograms	125
E Voltammograms	131
F Voltammograms	135
G SEM images for A1, A2, A3, A4 and A5	139
H SEM images for A6, A7, A8, A9, A10 and A11	144
I SEM images for B1, B2, B3, B4 and B5	150
J SEM images for A	155
K SEM images for B6, B7, B8, B9, B10 and B11	156
L SEM images for C1, C2, C3, C4 and C5	162
M SEM images for C6, C7, C8, C9, C10 and C11	167
N SEM-EDX spectrum	173
O SEM-EDX spectrum	174
P SEM-EDX spectrum	175